

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Phillip E. Byrd et al.

Application No.: 10/649,781

Confirmation No.: 5845

Filed: August 28, 2003

Art Unit: 2812

For: METHOD FOR TEMPORARILY ISOLATING
A DIE FROM A COMMON CONDUCTOR TO
FACILITATE WAFER LEVEL TESTING

Examiner: S. D. Isaac

AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. 1.116

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated March 20, 2007, finally rejecting claims 37-45 and 49-52, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.